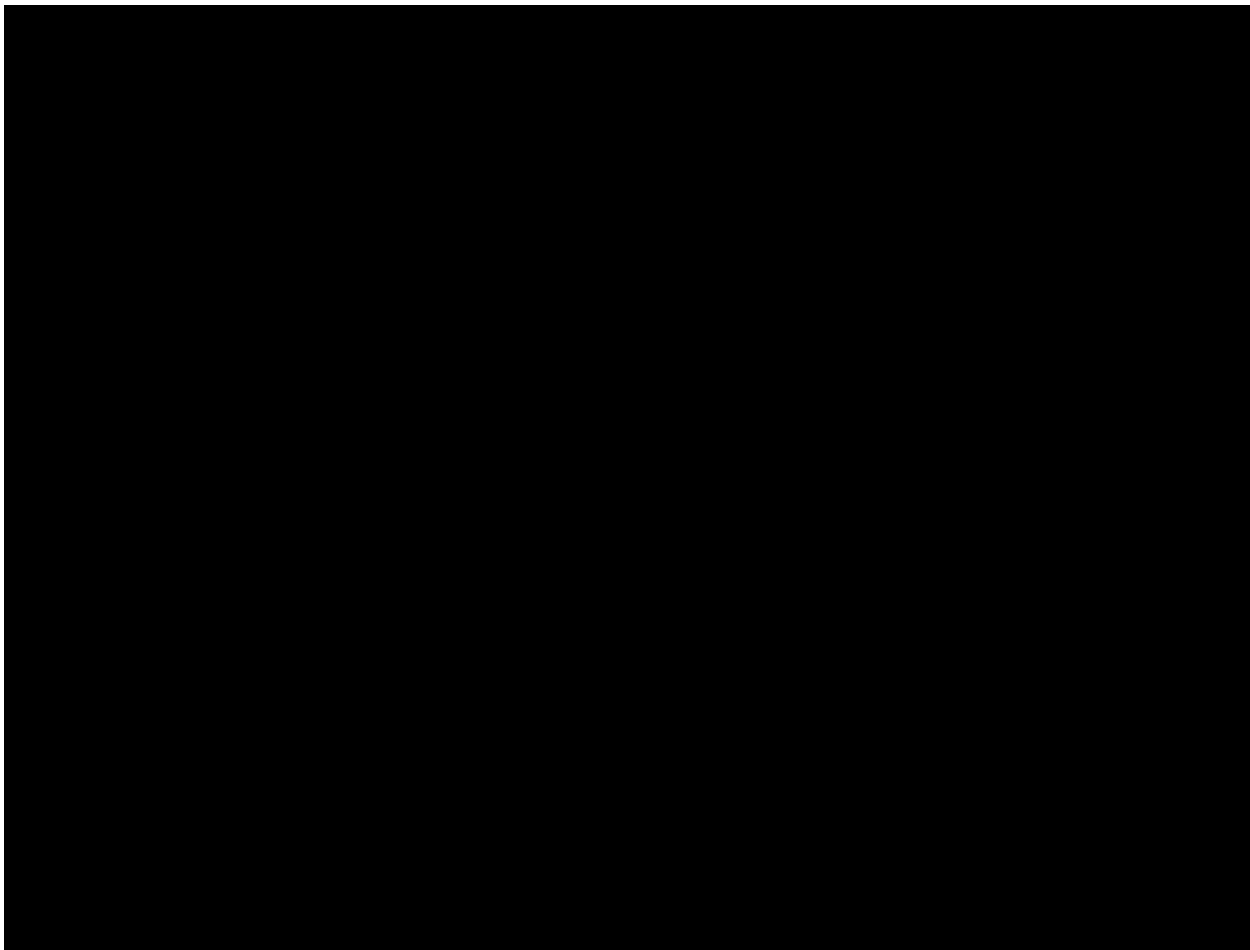


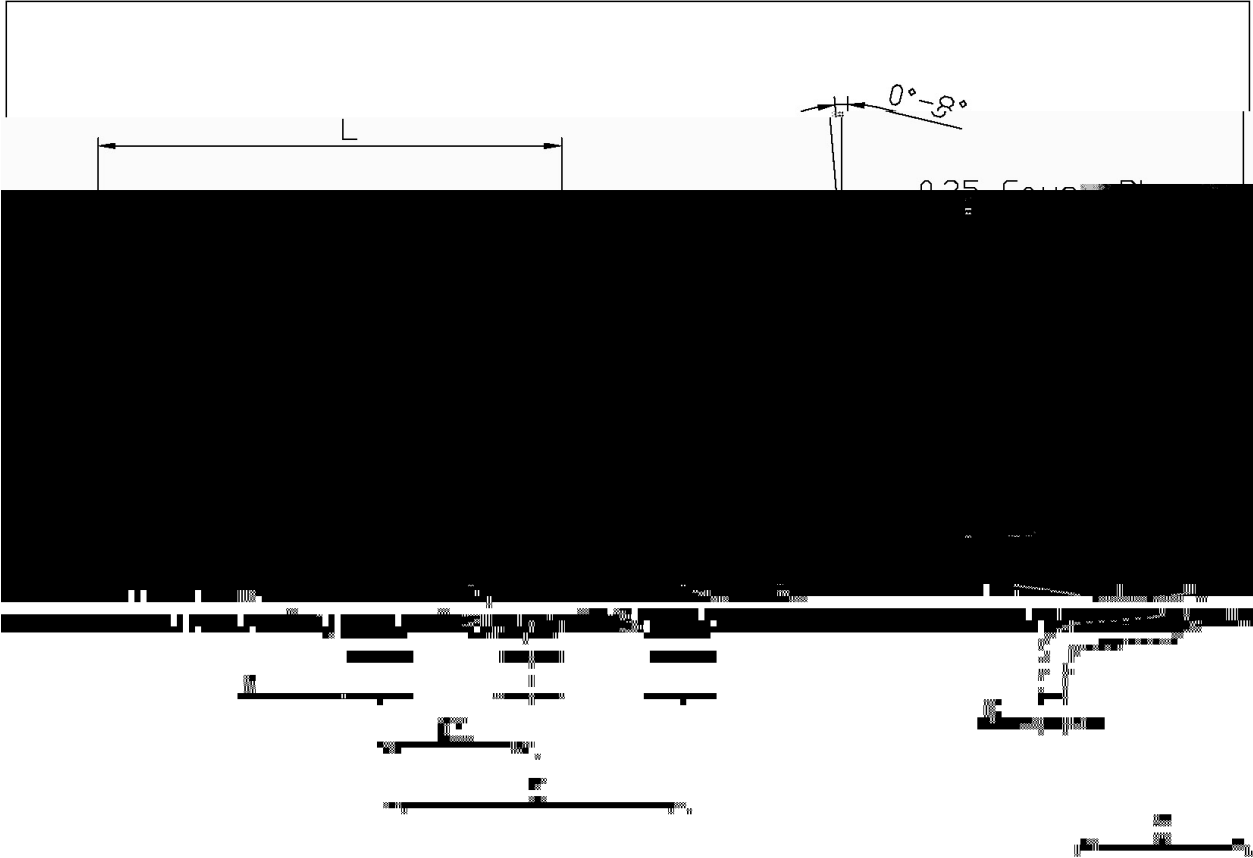
ᵛ ᵓᵒ	ᵛ N	ᵓᵒ ᵓ	D ᵓ
ᵓ ᵓ ᵓ ᵓ ᵓ ᵓ ᵓ	V _{IN_MAX}	30	V
ᵓ ᵓ ᵓ ᵓ ᵓ ᵓ ᵓ	V _{IN}	-0.3~30	V
CE ᵓ ᵓ ᵓ ᵓ ᵓ	V _{CE}	V _{IN} -0.3~V _{IN} +0.3	V
ᵓ, ᵓ ᵓ	I _{OUT}	0~500	mA
ᵓ ᵓ ᵓ ᵓ ᵓ	P _D	0.3	W



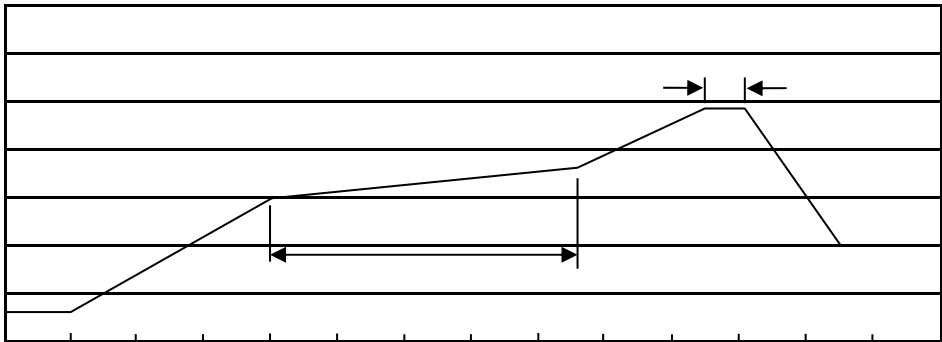
/ Functionl Block Diagram



/ Package Dimensions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



б " χ

1. 150~180 ℃, Time: 60~90sec;
2. 245±5 ℃, Duration: 5~0.5sec;
3. Cooling Speed: 2~10 ℃/sec.

Note:

- 1.Preheating:150~180 ℃, Time:60~90sec.
- 2.Peak Temp.:245±5 ℃, Duration:5~0.5sec.
3. Cooling Speed: 2~10 ℃/sec.

/ Resistance to Soldering Heat Test Conditions

260±5 ℃, Time: 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOT23-5/6	3,000	10	30,000	4	120,000	7 ×8	210×205×205	445×435×230

/ Notices

All information provided in this document is subject to legal disclaimers.